

1. The following Examiner's Amendment replaces the previous Examiner's Amendment mailed on 03/10/09.

2. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

In claim 31, line 1, ---30--- has been changed to ---29---.

In claim 88, line 2, ---49 or 53 to 49--- has been changed to --- or 53 to 58---.

Claims 49,59-87 and 139 have been canceled.

Claims 30-32,35,38-41,44 and 51 have been canceled.

New added claims 140-148 as follows:

Claim 140 (new) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the electronic component is a semiconductor wafer.

Claim 141 (new) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the area of the electronic component is a portion of a surface area of the electronic component.

Claim 142 (new) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the flexible elements are probe elements.

Claim 143 (new) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein there are electrical connections between the second substrates and the first substrate.

Claim 144 (new) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the first substrate is a space transformer.

Claim 145 (New) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the electronic component is a semiconductor wafer; and the flexible contact elements of the second substrate contact individual semiconductor dies on the semiconductor wafer.

Claim 146 (New) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the electronic component is a semiconductor wafer; and the flexible contact elements of the second substrate contacts at least one integrated circuit on the semiconductor wafer.

Claim 147 (New) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein the first substrate with the second substrate mounted thereto is mounted to an electrical testing apparatus by a plurality of electrical connections.

Claim 148 (New) A method according to any one of claims 29, 33, 34, 36, 37, 42, 43 or 53 to 58, wherein there is a least one second substrate is mounted to said first substrate.

3. Any inquiry concerning this communication or earlier communications from the examiner should be directed to VINH P. NGUYEN whose telephone number is 571-272-1964.

The examiner can normally be reached on 6:30AM-4:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, HA T. NGUYEN can be reached on 571-272-1678. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/VINH P NGUYEN/
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